

ABSTRACT OF THE DISCLOSURE

In the power distributor using a semiconductor switching element, input terminals 10I and 10L, output terminals 12A - 12J, connected to the element, and more preferably, the board terminals 30 and 32, are structured by a metallic plate, and arranged on the same plane perpendicular to the plate thickness. The metallic plate can be integrated by the resin mold, thereby the structure can be greatly simplified. The metallic plate can be produced by a greatly simple method by which, after the punching out of the metallic plate and the molding of the resin mold, a predetermined portion of the metallic plate is cut and the semiconductor switching element is mounted, and it can contribute to also the reduction of the cost.

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